



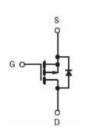
MJ P-Channel Enhancement Mode Power MOSFET

Description

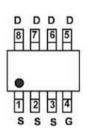
The MJ30P12S uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a load switch or in PWM applications.

General Features

- V_{DS} =-30V,I_D =-12A
 R_{DS(ON)} <25mΩ @ V_{GS}=-4.5V
 R_{DS(ON)} <15mΩ @ V_{GS}=-10V
- High power and current handing capability
- Lead free product is acquired
- Surface Mount Package



Schematic diagram



Application

Load switch

PWM applications

Power management



Marking and pin assignment

SOP-8 top view

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|----------|----------------|-----------|------------|------------|
| MJ30P12S | MJ30P12S | SOP-8 | Ø330mm | 12mm | 4000 units |

Absolute Maximum Ratings (TA=25℃ unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|----------|------------|------|
| Drain-Source Voltage | Vds | -30 | V |
| Gate-Source Voltage | Vgs | ±20 | V |
| Drain Current-Continuous (Tc =25°C) | lo | -12 | А |
| Drain Current-Continuous (Tc =100℃) | lo | -8.4 | А |
| Drain Current -Pulsed (Note 1) | Ідм | -48 | А |
| Maximum Power Dissipation (Tc =25°C) | Po | 3 | W |
| Maximum Power Dissipation (Tc =100°C) | Po | 1.3 | °C |
| Single pulse avalanche energy (Note 5) | Eas | 231 | mJ |
| Operating Junction and Storage Temperature Range | TJ ,TSTG | -55 To 150 | °C |

Thermal Characteristic

| Thermal Resistance, Junction-to-Ambient (Note 2) | Reja | 41.67 | °C/W | |
|--|------|-------|------|--|
|--|------|-------|------|--|

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Electrical Characteristics (TA=25°C unless otherwise noted)

| Parameter | Parameter Symbol Condition | | Min | Тур | Max | Unit |
|------------------------------------|----------------------------|---|-----|------|------|------|
| Off Characteristics | | 1 | 1 | | 1 | |
| Drain-Source Breakdown Voltage | BVDSS | V _{GS} =0V,I _D =-250µA | -30 | -33 | - | V |
| Zero Gate Voltage Drain Current | loss | Vds=-30V,Vgs=0V | - | - | -1 | μA |
| Gate-Body Leakage Current | lgss | VDS=±20V,VDS=0V | - | - | ±100 | nA |
| On Characteristics (Note 3) | I | I | 1 | | | |
| Gate Threshold Voltage | VGS(th) | Vos=Vgs,Io=-250µA | -1 | -1.5 | -3 | V |
| | | Vgs=-10V, Id=-10A | - | 11.5 | 15 | mΩ |
| Drain-Source On-State Resistance | Rds(on) | Vgs=-4.5V, Id=-7A | | 18 | 25 | mΩ |
| Forward Transconductance | G FS | V _{DS} =-10V,I _D =-10A | - | 20 | - | S |
| Dynamic Characteristics (Note 4) | | I | 1 | 1 | 1 | 1 |
| Input Capacitance | Ciss | | - | 1750 | - | PF |
| Output Capacitance | Coss | V⊳s=-15V,V₀s=0V F=1.0MHz | - | 215 | - | PF |
| Reverse Transfer Capacitance | Crss | | - | 180 | - | PF |
| Switching Characteristics (Note 4) | | 1 | 1 | 1 | 1 | 1 |
| Turn-on Delay Time | td(on) | | - | 9 | - | nS |
| Turn-on Rise Time | tr | V _{DD} =-15V, I _D =-10A | - | 8 | - | nS |
| Turn-Off Delay Time | td(off) | V_{GS} =-10V,R _{GEN} =1 Ω | - | 28 | - | nS |
| Turn-Off Fall Time | tr | | - | 10 | - | nS |
| Total Gate Charge | Qg | | - | 24 | _ | nC |
| Gate-Source Charge | Qgs | V _{DS} =-15V,I _D =-10A V _{GS} =-10V | - | 3.5 | _ | nC |
| Gate-Drain Charge | Qgd | | - | 6 | - | nC |
| Drain-Source Diode Characteristics | I | <u> </u> | | 1 | I | 1 |
| Diode Forward Voltage (Note 3) | Vsd | Vgs=0V,Is=-12A | - | - | -1.2 | V |
| Diode Forward Current (Note 2) | ls | | _ | _ | -12 | A |

Notes:

① Repetitive Rating: Pulse width limited by maximum junction temperature.

② Surface Mounted on FR4 Board, t ≤ 10 sec.

③ Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.

(4) Guaranteed by design, not subject to production

(5) Eas condition: Tj=25°C, V_DD=-15V, V_G=10V, L=0.5mH, Rg=25\Omega, Ias=-34A





150

50

Typical Electrical and Thermal Characteristics

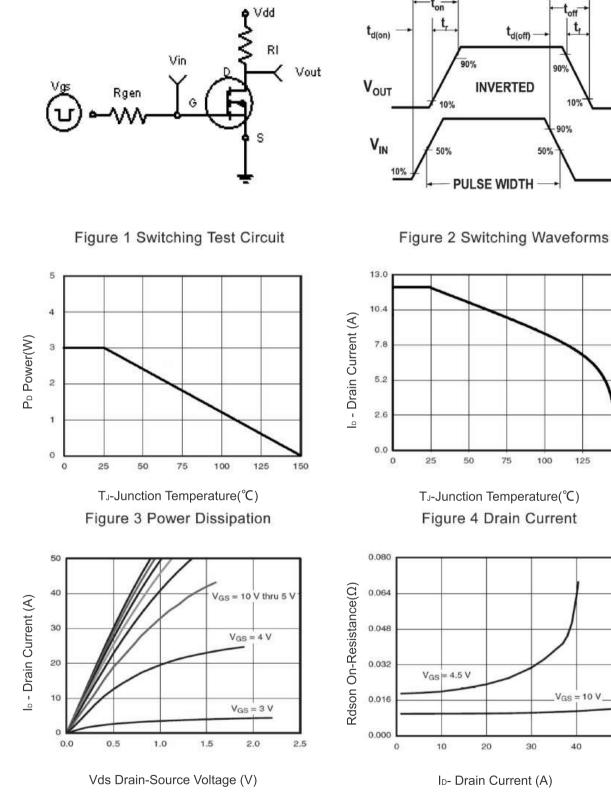


Figure 5 Output Characteristics

Figure 6 Drain-Source On-Resistance







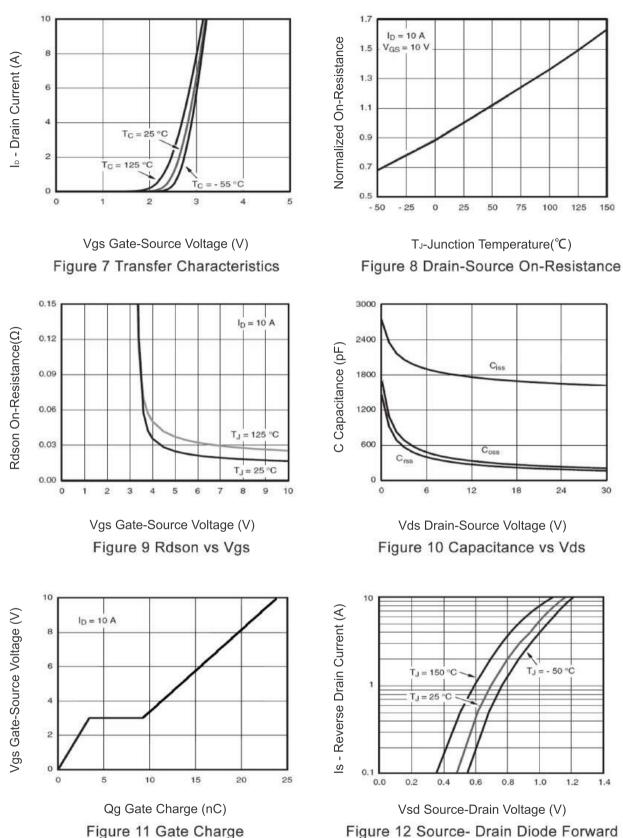
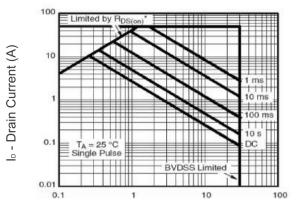


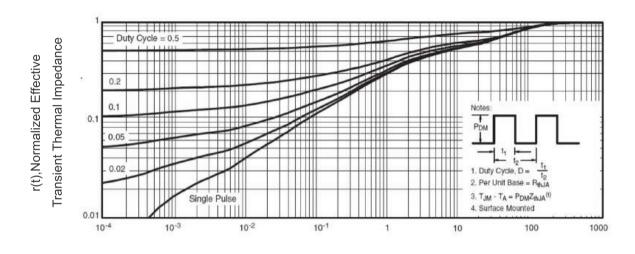
Figure 12 Source- Drain Diode Forward







Vds Drain-Source Voltage (V) Figure 13 Safe Operation Area

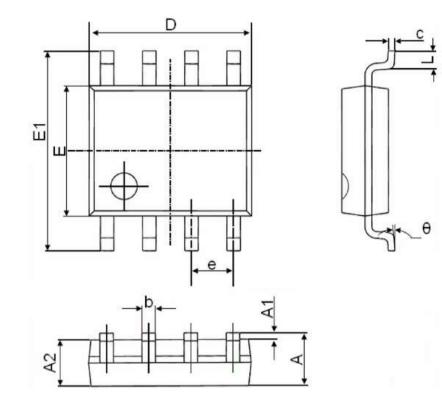


Square Wave Pluse Duration(sec) Figure 14 Normalized Maximum Transient Thermal Impedance





SOP-8 Package Information



| Compleal. | Dimensions In Millimeters | | Dimensions In Inches | | |
|-----------|---------------------------|------------|----------------------|-------|--|
| Symbol | Min. | Max. | Min. | Max. | |
| А | 1.350 | 1.750 | 0.053 | 0.069 | |
| A1 | 0.100 | 0.250 | 0.004 | 0.010 | |
| A2 | 1.350 | 1.550 | 0.053 | 0.061 | |
| b | 0.330 | 0.510 | 0.013 | 0.020 | |
| с | 0.170 | 0.250 | 0.006 | 0.010 | |
| D | 4.700 | 5.100 | 0.185 | 0.200 | |
| E | 3.800 | 4.000 | 0.150 | 0.157 | |
| E1 | 5.800 | 6.200 | 0.228 | 0.244 | |
| е | 1.270 | 1.270(BSC) | | (BSC) | |
| L | 0.400 | 1.270 | 0.016 | 0.050 | |
| θ | 0° | 8° | 0° | 8° | |





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